TestConX中国 China

征稿启事 TestConX 中国 2019

TestConX 中国 2019 研讨会， 2019 年 10 月 29 日（**周二**）上海，中国

TestConX 荣幸的宣布第 5 届电子测试技术研讨会将于 2019 年 10 月 29 日（周二）在上海举办。我们聚焦于电子行业的测试领域，提供从人员到解决方案的交流对接，千万别错过本届的行业盛会！

TestConX 技术委员会诚邀业内优秀人士来稿，尤其是 5G 无线测试的挑战和解决方案相关演讲稿，包括超高容量与毫米波技术。其他关于老化及测试主题的征稿依然有效。

TestConX 的每场演讲时长保持在 30 分钟（25 分钟主题演讲，5 分钟听众互动问答）。作者可以选择以中文或英语演讲，并只需准备一份 PPT 即可（无需文章）。

请于 2019 年 6 月 28 日前提交您（原创或未曾发表的演讲）的 250 到 500 字的主题摘要。

请通过以下方式提交：

- 在线填表 https://testconxchina.org/china-abstracts
- 或者发送电子邮件至 china-abstracts@testconxchina.org，包括演示文稿的标题，每位作者的完整联系信息（姓名，所属机构/公司名称，职位，电子邮件地址，电话号码和邮寄地址）以及演示者姓名。

特此 TestConX 组委会诚挚邀请业内优秀人士踊跃来稿！

初次来稿请提供 250 至 500 字的演讲摘要（内容原创且之前未发表，PPT 演讲材料即可，无需提供完整文章）、演讲标题、演讲者及作者完整信息（所有作者姓名，工作单位，职务，电子邮箱，电话，邮寄地址），并请注明是否能出席上海活动。

我们将对摘要进行审核并在 2019 年 7 月 12 日左右通知到作者。

演讲稿提交截止日期为 2019 年 9 月 13 日。

来稿语言：英语或中文。PPT 以英语为主，也可以选择增加中文对照。

请参考以下报告主题（不局限于此）：

封装测试中的电气和机械方面挑战

- 高频和高数据速率技术包括 5G 和毫米波
- 晶圆级封装 (WLP) 和面板级处理 (PLP)
- 更薄的封装和封装体叠层技术 (PoP)
- 球变形和封装内应力
- 高电流、高功率和高温期间测试
- 处理和更换组件的设计与注意事项
- ESD 管理
- 高精密开尔文连接
- 热量管理与建模
- 接插技术
- 电压电流极值，高低变化
- PoP, 裸片，片上系统(SOC),及 3D 封装测试
- 用于良好裸晶(KGD) 或终检的晶圆级芯片规模测试 (WLCSP)
- 无铅技术
- 温湿度偏差测试 (THB), 加速寿命试验(HAST) 或其他特殊场景

测试进程和操作上的挑战

- 片上级天线封装测试
- 老化测试的运作
- 接插件维修，清洗及重新镀层方法
- 价值工程:降低占用成本,实现低成本测试
- 大规模并行及非单一测试(晶圆级和面板级)
- 减少鉴定测试和生产时间的策略
- 接插件与 PCB 验证，检查和鉴定
- 剥离测试和托盘测试
- 针对关键人物和医疗应用的高可靠性测试
- 微机电系统 (MEMS) 和非电气 (声、光、磁、流体, 等.) 模拟测试

模块和产品测试上的挑战

- 治具与测试探针
- 电测自动化
- 物料的自动化处理
- 大规模和批量场景下的无线测试
- 热量控制

印刷线路板(PCB)设计和制造上的挑战

- 高温老化的场景应用
- 高数据速率测试应用
- 空间变形及超细间距
- 板间互联

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TestConX China 2019

Shanghai – Tuesday October 29, 2019

TestConX China is pleased to announce the 5th annual workshop will be held on Tuesday October 29, 2019 in Shanghai. *Don't miss the preeminent China event focused on connecting electronic test professionals to solutions.*

The TestConX China Technical Program Committee is seeking presentations that highlight the challenges and solutions for 5G wireless testing including ultra-high volume operations and millimeter-wave technology. Other proposals on a broad range of test and burn-in topics, as illustrated below, are also highly valued.

Each presentation at TestConX China is provided a thirty-minute presentation slot (approximately 25 minutes for the presentation with 5 minutes for questions and answers). Authors may choose to present in English or Mandarin. And authors only need to prepare a PowerPoint presentation. (There is no paper to write.)

Please submit a 250 to 500 word abstract for presentations or posters of your original, previously unpublished, technical presentation by June 28, 2019.

Submit via:

- Online form https://testconxchina.org/china-abstracts

or

- Email china-abstracts@testconxchina.org including title of presentation, complete contact information (name, affiliation/company name, job title, email address, phone number, and mailing address) for each author, and name of presenter. Be sure to indicate availability to present at Shanghai.

Abstracts will be reviewed and authors will be notified around July 12, 2019.

Presentations submissions are due September 13, 2019.

Language: Presentation in English or Mandarin. PowerPoint slides in English with the option to also create Chinese slides.

Topics of interest include, but are not limited to:

Electrical & Mechanical Challenges in package testing

- High frequency and high data rate techniques and technologies including 5G and mm-wave
- Wafer Level Packages (WLP) and Panel Level Processing (PLP)
- Thinner Packages & Package-on-Package (PoP)
- Ball deformation & package stress
- High current, high power, and/or high temperature device testing
- Handler & change kit designs and considerations
- Managing ESD
- Fine Pitch Kelvin Contacting
- Thermal management and modelling
- Contact technology
- Voltage and current extremes, high and low
- PoP, Bare Die, system on a chip (SOC), and 3D package testing
- Wafer level chip scale (WLCSP) test for Known Good Die (KGD) or final test
- Lead-Free
- Temperature/Humidity/Bias (THB), highly accelerated stress test (HAST) or other special

Test Process & Operational Challenges

- Over the Air (OtA) and Antenna in Package (AiP) testing
- Test & Burn-in floor operations
- Socket repair, cleaning, and re-plating methods
- Value Engineering: reducing cost of ownership, achieving low-cost test, burn-in, etc.
- Massively parallel and non-singulated test (Wafer Lavel and Panel Level)
- Test strategies for reducing qualification and production time
- Socket & PCB verification, checkout & qualification
- Strip Testing and Test-in-Tray
- High reliability testing for mission critical and medical applications
- Microelectromechanical system (MEMS) and non-electrical (optical, fluidic, magnetic, acoustic, etc.) stimuli testing

Module & Product Test Challenges

- Fixturing and test contact
- Test automation
- Automated material handling
- Wireless testing at scale / high volume
- Thermal control

Printed Circuit Board (PCB) Design & Manufacturing Challenges

- For high temperature Burn-in board applications
- High data rate test applications
- Space Transformers and Ultra-fine pitch
- Board to Board Interconnects

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